ICS301-28

Dual Output Clock Synthesizer

Description

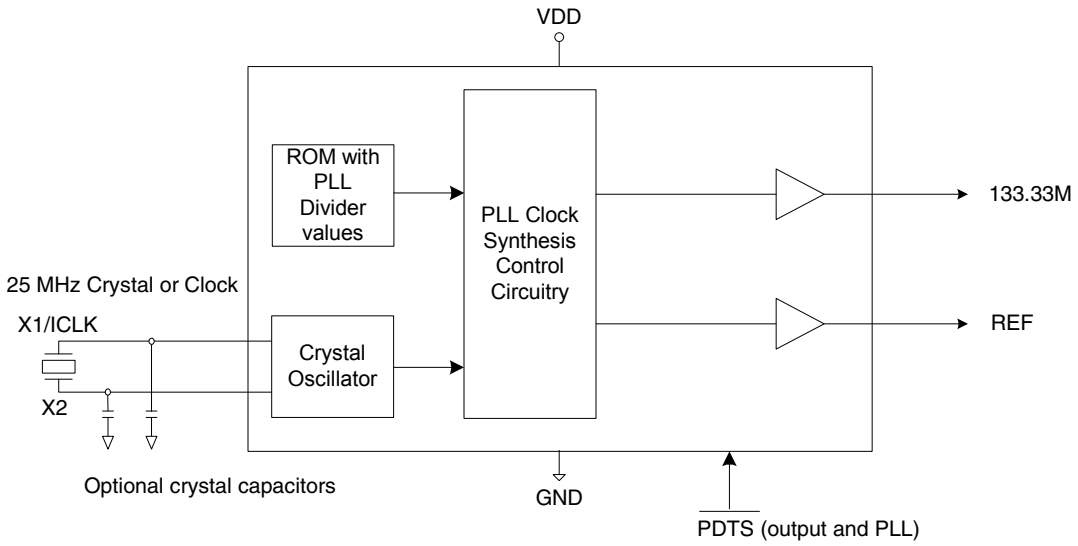
The ICS301-28 is a low cost frequency generator. Using analog/digital Phase-Locked-Loop (PLL) techniques, the device accepts a 25 MHz crystal or clock input to produce an output clock of 133.33 MHz and a reference output.

The device also has a power down feature that tri-states the clock outputs and turns off the PLL when the $\overline{\text{PDTS}}$ pin is taken low.

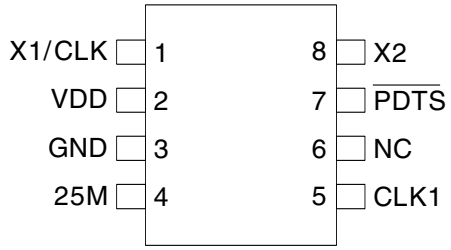
Features

- 8 pin SOIC package – Pb-free, RoHS compliant
- Zero ppm synthesis error
- Input clock or crystal frequency of 25 MHz
- Duty cycle of 45/55
- Operating voltage of 3.3 V
- Advanced, low power CMOS process

Block Diagram



Pin Assignment



8 pin (150 mil) SOIC

Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	X1/CLK	XI	Connect this pin to a 25 MHz clock or crystal input.
2	VDD	Power	Connect to +3.3V.
3	GND	Power	Connect to ground.
4	25M	Output	25 MHz reference output.
5	CLK1	Output	133.33 MHz CMOS level clock output.
6	NC	-	Do not connect anything to this pin.
7	$\overline{\text{PDTS}}$	Input	Powers down entire chip. Tri-states CLK1 output when low. Internal pull-up.
8	X2	XO	Connect this pin to a 25 MHz crystal. Float for clock input.

External Components

Series Termination Resistor

Clock output traces over one inch should use series termination. To series terminate a 50Ω trace (a commonly used trace impedance), place a 33Ω resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is 20Ω

Decoupling Capacitor

As with any high performance mixed-signal IC, the ICS301-28 must be isolated from system power supply noise to perform optimally.

A decoupling capacitor of 0.01µF must be connected between VDD and the PCB ground plane.

Crystal Load Capacitors

The device crystal connections should include pads for small capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance. Because load capacitance can only be increased in this trimming process, it is important to keep stray capacitance to a minimum by using very short PCB traces (and no vias) between the crystal and device. Crystal capacitors must be connected from each of the pins X1 and X2 to ground.

The value (in pF) of these crystal caps should equal (C_L -6pF)*2. In this equation, C_L= crystal load capacitance in pF. Example: For a crystal with a 16 pF load capacitance, each crystal capacitor would be 20 pF [(16-6) x 2 = 20].

PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

1) The 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.

2) The external crystal should be mounted just next to the device with short traces. The X1 and X2 traces should not be routed next to each other with minimum spaces, instead they should be separated and away from other traces.

3) To minimize EMI the 33Ω series termination resistor, if needed, should be placed close to the clock output.

4) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the ICS301-28. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the ICS301-28. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7V
All Inputs and Outputs	-0.5V to VDD+0.5V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Junction Temperature	175° C
Soldering Temperature	260° C

Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature	0		+70	° C
Power Supply Voltage (measured in respect to GND)	+3.15	+3.3	+3.45	V

DC Electrical Characteristics

Unless stated otherwise, VDD = 3.3V ±5%, Ambient Temperature 0 to +70° C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		3.15	3.3	3.45	V
Supply Current	IDD	No load, $\overline{PDTS}$=1		11		mA
		No load, $\overline{PDTS}$=0		20		µA
Input High Voltage	V_{IH}	$\overline{PDTS}$ pin	VDD-0.5			V
Input Low Voltage	V_{IL}	$\overline{PDTS}$ pin			0.4	V
Input High Voltage	V_{IH}	ICLK pin	VDD/2+1			V
Input Low Voltage	V_{IL}	ICLK pin			VDD/2-1	V
Output High Voltage (CMOS High)	V_{OH}	I_{OH} = -8 mA	VDD-0.4			V
Output High Voltage	V_{OH}	I_{OH} = -12 mA	2.4			V
Output Low Voltage	V_{OL}	I_{OL} = 12mA			0.4	V
Short Circuit Current	I_{OS}			±70		mA
Nominal Output Impedance	Z_O			20		Ω
Internal pull-down resistor	R_{PD}	CLK outputs		510		kΩ
Input Capacitance	C_{IN}	$\overline{PDTS}$ pin		5		pF

AC Electrical Characteristics

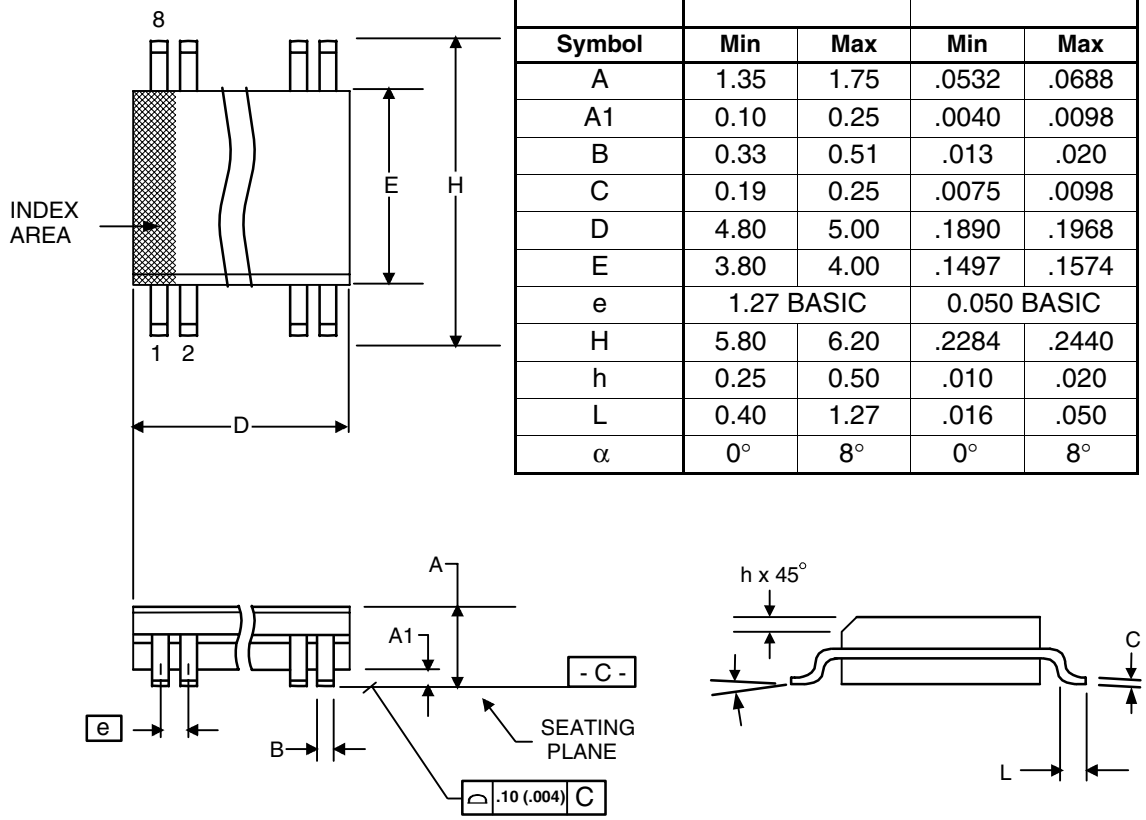
Unless stated otherwise, VDD = 3.3V ±5%, Ambient Temperature 0 to +70° C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Rise Time	t_{OR}	20% to 80%, Note 1		1.2		ns
Output Fall Time	t_{OF}	80% to 20%, Note 1		1.2		ns
Duty Cycle		at VDD/2, Note 1	45	50	55	%
Cycle Jitter, 133.33MHz	t_{ja}	peak to peak		±110		ps
Cycle Jitter , Ref 25MHz	t_{ja}	peak to peak		±220		ps
Input Frequency				25		MHz
Output Frequency Synthesis Error				0		ppm
Output Enable Time, $\overline{PDTS}$ high to output on				250		µs
Output Disable Time, $\overline{PDTS}$ low to tri-state				20		ns

Note 1: with 15pF load.

Package Outline and Package Dimensions (8 pin SOIC, 150 Mil. Body)

Package dimensions are kept current with JEDEC Publication No. 95



	Millimeters		Inches	
Symbol	Min	Max	Min	Max
A	1.35	1.75	.0532	.0688
A1	0.10	0.25	.0040	.0098
B	0.33	0.51	.013	.020
C	0.19	0.25	.0075	.0098
D	4.80	5.00	.1890	.1968
E	3.80	4.00	.1497	.1574
e	1.27 BASIC		0.050 BASIC	
H	5.80	6.20	.2284	.2440
h	0.25	0.50	.010	.020
L	0.40	1.27	.016	.050
α	0°	8°	0°	8°

Ordering Information

Part / Order Number	Marking	Shipping packaging	Package	Temperature
301M-28LF	301M-28L (top line) YYWW$$ (3nd line)	Tubes	8 pin SOIC	0 to +70° C
301M-28LFT		Tape and Reel	8 pin SOIC	0 to +70° C

"LF" suffix to the part number denotes Pb-Free configuration, RoHS compliant.